

Description

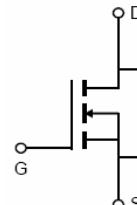
The series of devices uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(on)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

General Features

- $V_{DS} = 120V, I_D = 90A$
- $R_{DS(on)} = 7.7m\Omega$, typical (TO-220)@ $V_{GS} = 10V$
- $R_{DS(on)} = 7.5m\Omega$, typical (TO-263)@ $V_{GS} = 10V$
- Excellent gate charge $\times R_{DS(on)}$ product(FOM)
- Very low on-resistance $R_{DS(on)}$
- 175 °C operating temperature
- Pb-free lead plating



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VST12N075-T3	VST12N075	TO-220C	-	-	-
VST12N075-TC	VST12N075	TO-263	-	-	-

Absolute Maximum Ratings ($T_c = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	120	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	90	A
Drain Current-Continuous($T_c = 100^\circ C$)	$I_D(100^\circ C)$	64	A
Pulsed Drain Current ^(Note 1)	I_{DM}	360	A
Maximum Power Dissipation	P_D	140	W
Derating factor		0.93	W/°C
Single pulse avalanche energy ^(Note 4)	E_{AS}	352	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 175	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.07	°C/W
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Electrical Characteristics ($T_c=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	120		-	V
Zero Gate Voltage Drain Current	I_{DSS}	$\text{V}_{\text{DS}}=120\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$\text{V}_{\text{GS}}=\pm20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\mu\text{A}$	2.0	3.0	4.0	V
Drain-Source On-State Resistance	$\text{R}_{\text{DS}(\text{ON})}$	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=45\text{A}$	TO-220	-	7.7	8.0
			TO-263		7.5	8.0
Forward Transconductance	g_{FS}	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=45\text{A}$		55	-	S
Dynamic Characteristics (Note 3)						
Input Capacitance	C_{iss}	$\text{V}_{\text{DS}}=60\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{F}=1.0\text{MHz}$	-	3715	-	pF
Output Capacitance	C_{oss}		-	275	-	pF
Reverse Transfer Capacitance	C_{rss}		-	18	-	pF
Switching Characteristics (Note 3)						
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$\text{V}_{\text{DD}}=60\text{V}, \text{I}_D=45\text{A}, \text{V}_{\text{GS}}=10\text{V}, \text{R}_G=1.6\Omega$	-	20	-	nS
Turn-on Rise Time	t_r		-	16	-	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	45	-	nS
Turn-Off Fall Time	t_f		-	12	-	nS
Total Gate Charge	Q_g	$\text{V}_{\text{DS}}=60\text{V}, \text{I}_D=45\text{A}, \text{V}_{\text{GS}}=10\text{V}$	-	58	-	nC
Gate-Source Charge	Q_{gs}		-	21	-	nC
Gate-Drain Charge	Q_{gd}		-	14.5	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 2)	V_{SD}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_s=45\text{A}$	-	-	1.2	V
Diode Forward Current	I_s		-	-	90	A
Reverse Recovery Time	t_{rr}	$\text{T}_J = 25^\circ\text{C}, \text{I}_F = 90\text{A}$ $\text{di}/\text{dt} = 100\text{A}/\mu\text{s}$ (Note 3)	-	65	-	nS
Reverse Recovery Charge	Q_{rr}		-	105	-	nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
3. Guaranteed by design, not subject to production
4. EAS condition : $\text{T}_J=25^\circ\text{C}, \text{V}_{\text{DD}}=50\text{V}, \text{V}_{\text{G}}=10\text{V}, \text{L}=0.25\text{mH}, \text{R}_G=25\Omega$

Typical Electrical and Thermal Characteristics

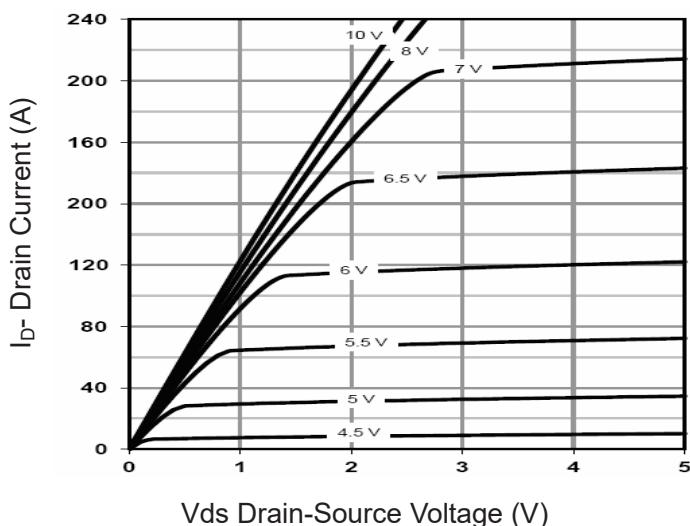


Figure 1 Output Characteristics

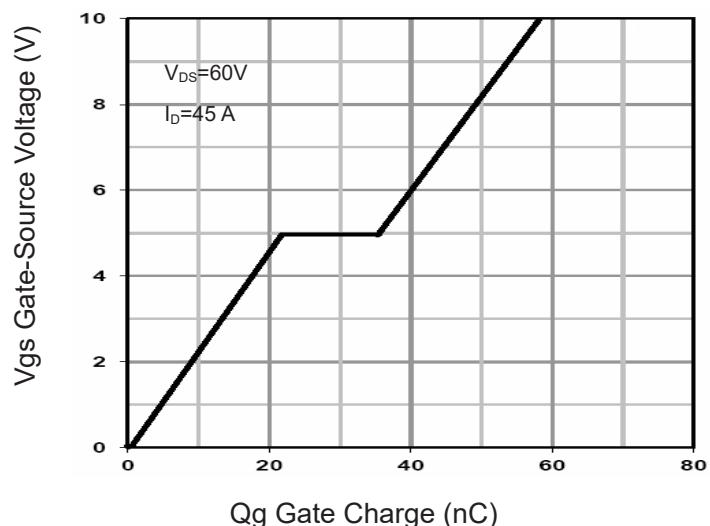


Figure 4 Gate Charge

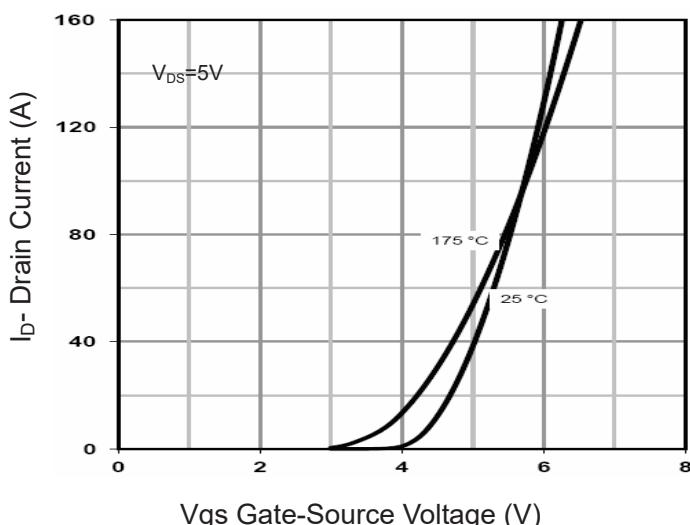


Figure 2 Transfer Characteristics

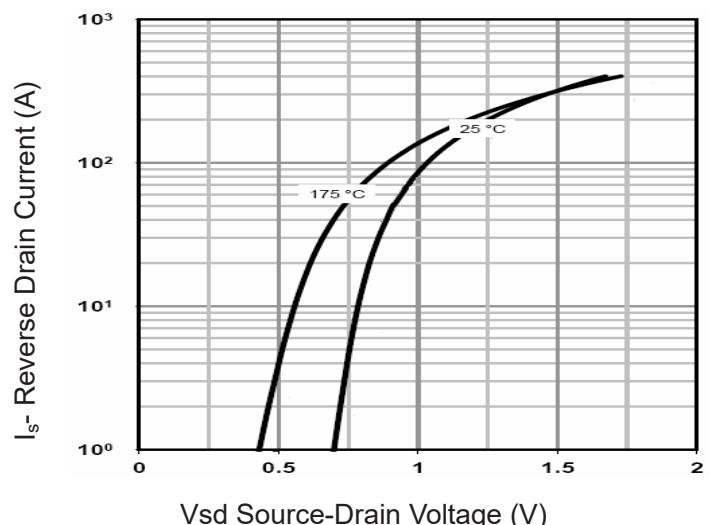


Figure 5 Source- Drain Diode Forward

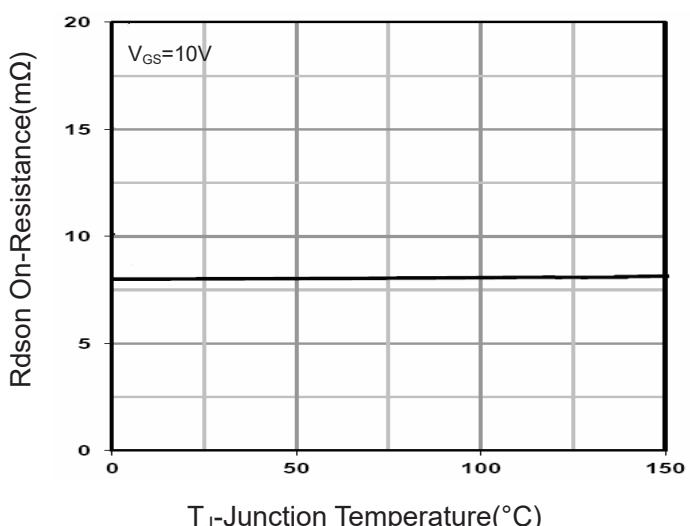


Figure 3 Rdson-Junction Temperature

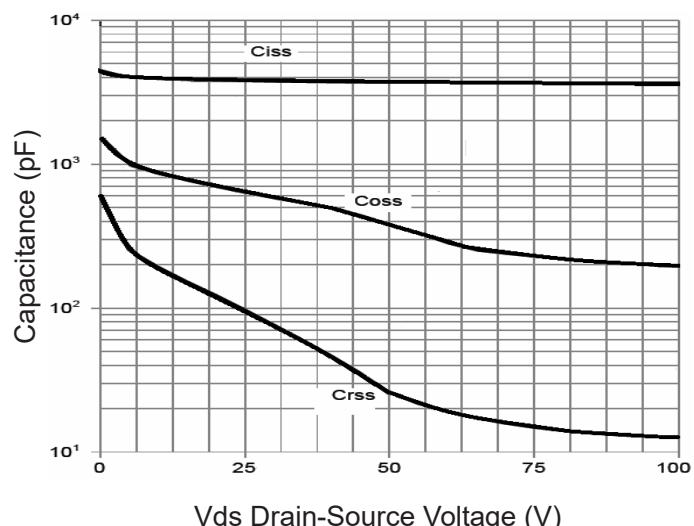
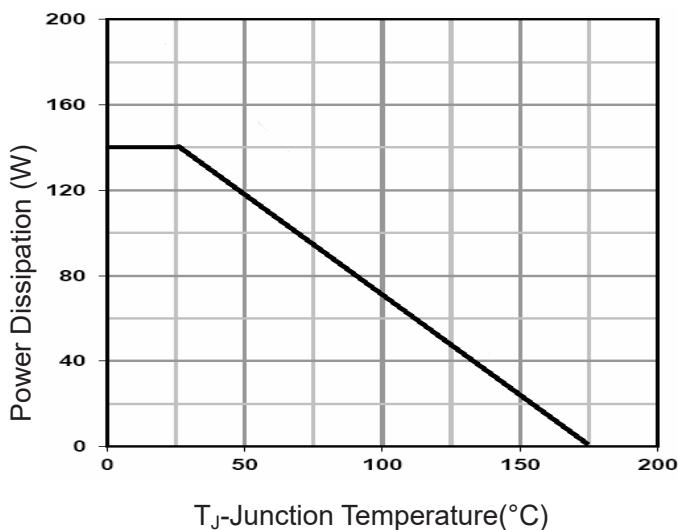
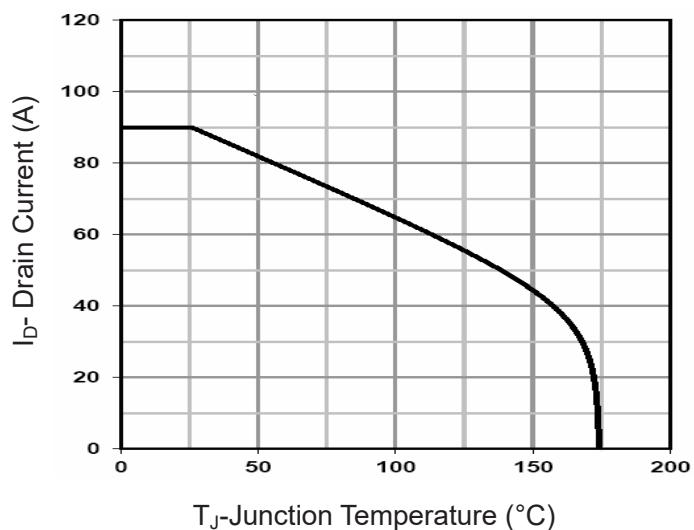
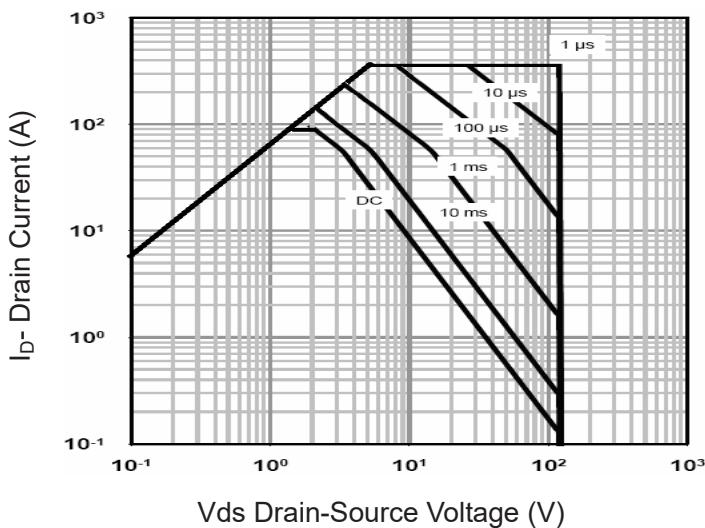
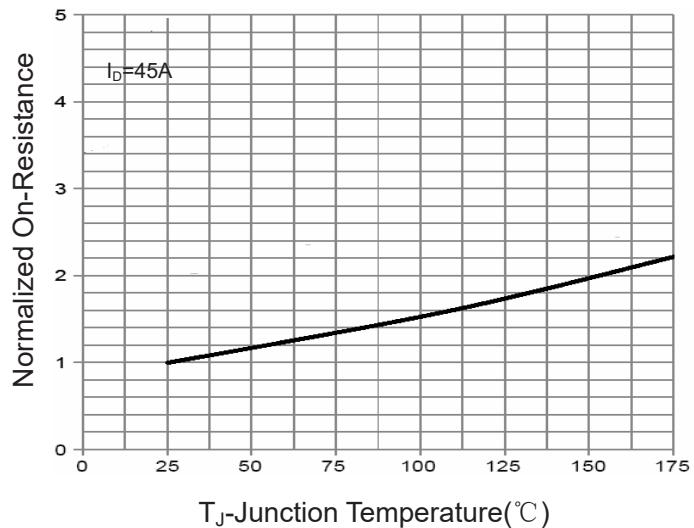
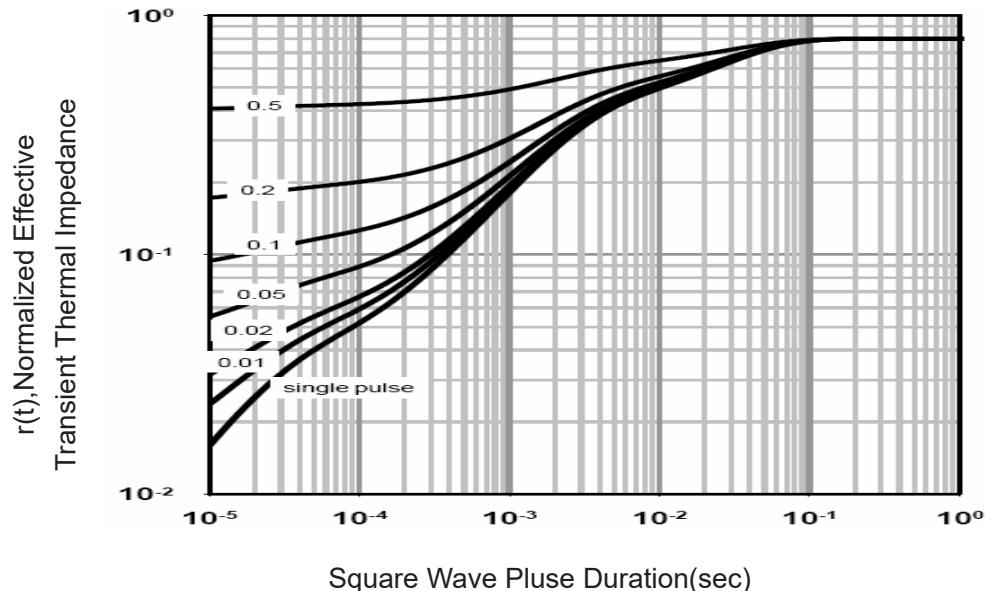


Figure 6 Capacitance vs Vds


Figure 7 Power De-rating

Figure 9 Current De-rating

Figure 8 Safe Operation Area

Figure 10 Rdson-Junction Temperature

Figure 11 Normalized Maximum Transient Thermal Impedance